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2001 Staas & Halsey LLP To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. Name of conveying party(ies): Jin-soo LEE Se-hyun LYU 2. Name and Address of receiving party(ies): Samsung Electronics Co., Ltd. 416, Maetan-dong, Paldal-gu Suwon-city, Gyunggi-do Republic of Korea Nature of conveyance: 3. Assignment Х Merger Security Agreement Change of Name Other: Execution Date(s): May 15, 2003 4. Application number(s) or patent number(s): This document is being filed together with a new application: The execution date(s) of the application is/are: May 15, 2003 (a) The title is: CONTACT SHOCK DAMPENING AND DEVELOPMENT NIP FORMING (b) APPARATUS FOR DEVELOPERS This document is being filed after filing of the application: Patent Application No(s). __/___, filed _____ (a) (b) Patent No(s). . issued Name and address of party to whom correspondence concerning document should be mailed: 5. STAAS & HALSEY LLP Our Docket: 1349.1196 Attention: Michael D. Stein 05/23/2003 SZEWDIE1 00000042 1044; 700 Eleventh Street, N.W., Suite 500 01 FC:8021 Washington, D.C. 20001 Total number of applications and patents involved: _1 6. Total fee (37 CFR 3.41)..... (\$ 40.00 per Assignment) 7. Enclosed Х Authorized to be charged to deposit account. Deposit Account No.: 19-3935 (Any underpayment is authorized to be charged to this Deposit Account) 8. (Attach duplicate copy of this page if paying by deposit account) 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Michael D. Stein, Reg. No. 37,240 May 22, 2003 Name of Person Signing Signature Total number of pages including cover sheet: 2 DO NOT USE THIS SPACE

Docket No.: 1349.1196

U.S. ASSIGNMENT

S&H 1/00

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by (Insert Name(s) & Address(es) of ASSIGNEE(S))

Samsung Electronics Co., Ltd. 416, Maetan-dong, Paldal-gu Suwon-city, Gyunggi-do Republic of Korea

RECORDED: 05/22/2003

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled (*Title of Invention*)

CONTACT SHOCK DAMPENING AND DEVELOPMENT NIP FORMING APPARATUS FOR DEVELOPERS

executed on even date herewith or, if not so executed, was:	and/or for which application for Letters Patent of the United States wa
(a) executed on;	(Insert date of execution of application, if not concurrent)
(b) filed on	Any registered attorney of STAAS & HALSEY LLP, 700 Eleventh Street, N.W., Washington, D.C. 20001 (202/434-1500) is hereby authorized to insert in (b) the specified data, when known.
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	tates granted on said application and any continuation, division, renewal, for the full term or terms for which the said Letters Patent(s) may be granted "said application(s) and Letters Patent(s)").
which the ASSIGNEE may deem necessary, desirable or expedincluding in the preparation and prosecution of said application reexamination, or public use proceeding, and in any litigation of the contract of th	EE and without charge to but at the expense of said ASSIGNEE, to do all actient, for securing, maintaining and enforcing protection for said invention, (s) and the issuance of said Letters Patent(s), in any interference, reissue, or other legal proceeding which may arise or be declared in relation to same, including separate assignments and declarations, taking all rightful oaths, ince.
IN WITNESS WHEREOF, the undersigned inventor(s) has (Typed Name & Signature of Inventor(s))	(have) affixed his/her/their signature(s). (Date) (Typed Name & Signature of Witness(es))
LEE JIN SCO Ma	y 15, 2003 (et Gr7)
Jin-soo LEE	Eun-ji LEE May 15, 2003 (le Carri
Se-byun LYU	May 15, 2003 () Un () Eun-ji LEE
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PATENT REEL: 014107 FRAME: 0994